

e-Manufacturing System for Next-generation Semiconductor Production

Yasutsugu Usami
Isao Kawata
Hideyuki Yamamoto
Hiroyoshi Mori
Motoya Taniguchi, Dr. Eng.

OVERVIEW: Next-generation semiconductor factories need to support miniaturization below 100 nm and have higher production efficiency, mainly of 300-mm-diameter wafers. Particularly to reduce the price of semiconductor devices, shorten development time [thereby reducing the TAT (turn-around time)], and support frequent product changeovers, semiconductor manufacturers must enhance the productivity of their systems. To meet these requirements, Hitachi proposes solutions that will support e-manufacturing on the next-generation semiconductor production line (see Fig. 1).

INTRODUCTION

THE semiconductor and electronic part industries currently face two major challenges: implementing IT-based structural reform and improving profitability.

The establishment of IT-based “e-business” and “e-manufacturing” is drawing much attention as a way to improve on the development and equipment investment that put negative impact on profitability.

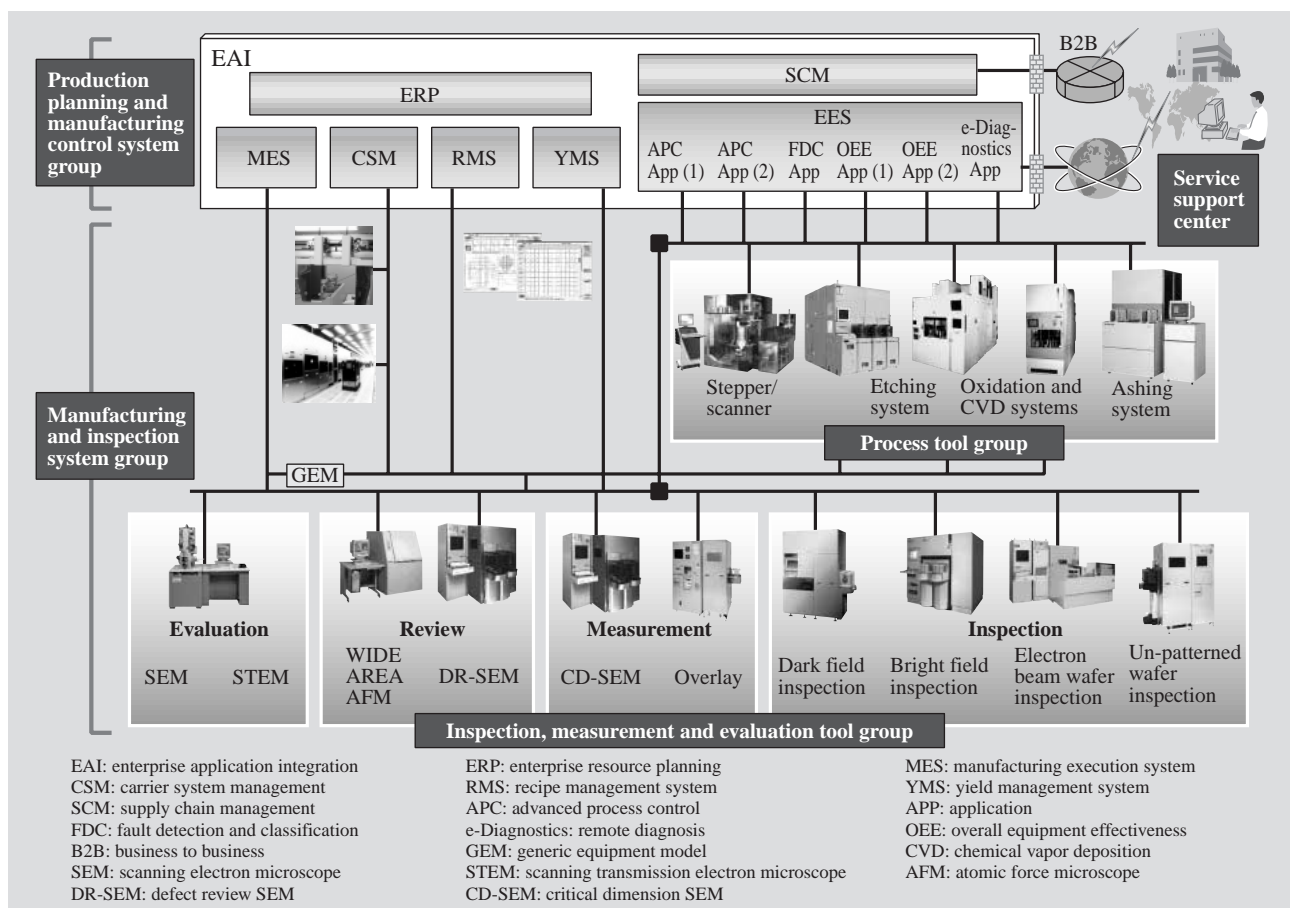


Fig. 1—Overall Configuration of e-Manufacturing Proposed by Hitachi for Next-generation Semiconductor Production Line.

In e-manufacturing on the next-generation semiconductor production line, a production planning and manufacturing control system group, a manufacturing and inspection system group, and a service support center should be linked using IT (information technology) for efficient utilization of information in order to enhance productivity.

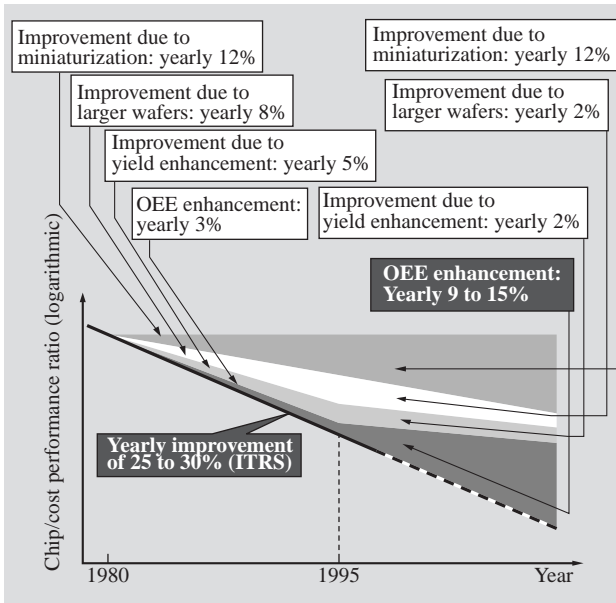


Fig. 2—Reduction in Cost/Performance Ratio of Semiconductor Chips.
Reduction in the chip/cost performance ratio requires an annual increase in the OEE of 9 to 15%.

The trend in the cost/performance ratio of semiconductor chips is illustrated in Fig. 2. Device miniaturization and the increase in the number of obtainable chips due to larger diameter wafers have contributed to reducing the ratio. Performance enhancement through device miniaturization will continue according to the International Technology Roadmap for Semiconductors (ITRS). On the other hand, the introduction of larger diameter wafers, particularly the recent advent of 300-mm wafers, has substantially increased the investment needed in equipment investment. Moreover, the increase in the

size of the process and transfer equipment and the introduction of single-wafer processing has complicated the equipment design process.

Enhancing the yield has been the focus of process control improvement over the last ten years. Enhancement has been achieved by continually improving the equipment used for measurement, inspection, and analysis/evaluation. Up to about ten years ago, the inspection system for process control accounted for about 5% of the total investment in chip manufacturing equipment. The ratio is now between 10 and 20%. Moreover, the adoption of higher sensitivity inspection systems has increased data output, which has increased analysis time and thus production costs. Thus, the introduction of inspection systems, whose original objective was to lower the chip cost/performance ratio, had the opposite effect of raising cost. To reduce the chip cost/performance ratio even more, attention is now turning to improving the utilization efficiency of the manufacturing equipment, i.e., OEE (overall equipment effectiveness).

Fig. 3 shows how semiconductor manufacturers currently utilize their equipment (based on actual operation) and the improvements requested. As shown in the chart, OEE is only about 43%, meaning that more than half the time the equipment is not contributing to actual production.

As shown by the chart in Fig. 3, a major factor in the reduced OEE is the length of time spent to set up the equipment. This includes the time spent determining whether the previous process was performed properly and changing the processing parameters. Another major factor is checking by test wafers. This includes a preliminary check of particle

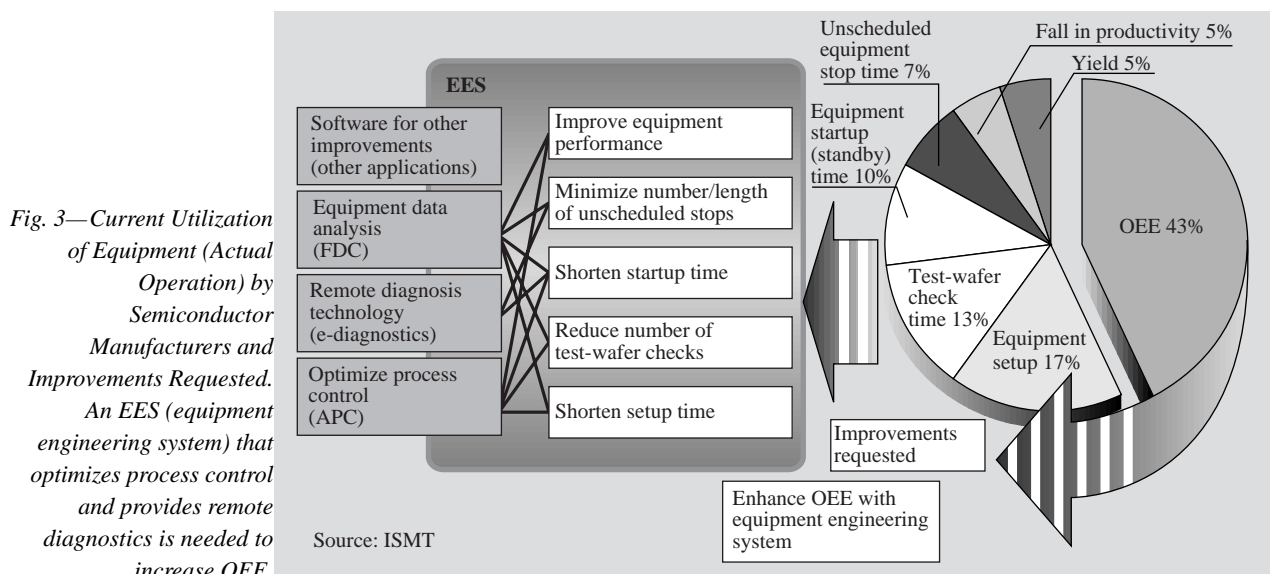


Fig. 3—Current Utilization of Equipment (Actual Operation) by Semiconductor Manufacturers and Improvements Requested. An EES (equipment engineering system) that optimizes process control and provides remote diagnostics is needed to increase OEE.

generation in the process equipment and optimization of the exposure conditions, i.e., “trial exposure.” These conditions have normally been optimized in the development stage, and in future microlithography, process tolerances will be much smaller, and more time will be needed for optimizing them due to mechanical differences between process devices. At the same time, reducing equipment startup (standby) time and unscheduled equipment stop time require a person with process knowhow and expertise in equipment control techniques, which places an additional burden on the operator.

An EES (equipment engineering system) would help improve all the above factors because it would acquire, analyze, and optimize the process data and working status data of the equipment. Specifically, an EES has a database for storing the diverse and voluminous data obtained from the equipment and functions that use this data for APC (advanced process control), e-diagnostics, and FDC (fault detection and classification).

This paper describes the optimum process control technology and e-diagnostics developed by Hitachi as core technologies supporting e-manufacturing and their expanded use in the future.

TECHNOLOGIES SUPPORTING e-MANUFACTURING

Device miniaturization is narrowing the error range allowed in each chip-manufacturing process. Variations that used to be allowed are now affecting device characteristics significantly or even causing defects. Two technologies have been developed to overcome this problem: APC and e-diagnostics. APC controls the processes so as to minimize unevenness and variations in accuracy due to differing process conditions, device specifications, wafer states, etc., thereby stabilizing device quality. e-diagnostics reduces maintenance costs and supports preventive maintenance by enabling manufacturing equipment to be diagnosed on-site via the Internet. This means that an authorized service technician can access and diagnose production equipment without having to first travel to the location, thereby saving time and money.

Advanced Process Control in Lithography Process

Fig. 4 illustrates the application of the ARGUS* APC to a lithography process composed of multiple exposure systems and a resist coating/developing system called “Track.” To maintain process normalcy,

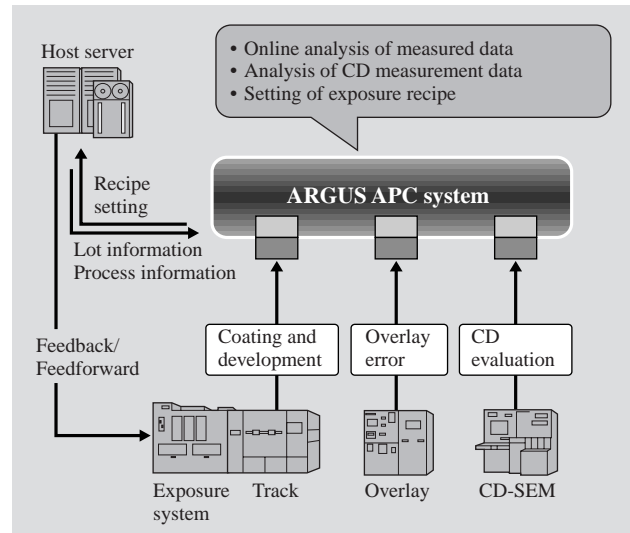


Fig. 4—Application of ARGUS APC to Lithography Process. ARGUS detects and analyzes changes after each process completes and corrects the processing recipe as required to stabilize the process.

an overlay error measuring system called “Overlay” and a CD measuring CD-SEM play important roles.

Hitachi as a CD-SEM and Overlay maker/supplier has been tracking the needs for inspection control of the lithography process as expressed by many customers/users and working to stabilize the process. Based on the knowledge and information it has obtained, Hitachi developed the ARGUS APC system in collaboration with New Vision Systems. ARGUS is an integrated system that monitors changes in a process while gathering data from such measuring systems as Overlay and CD-SEM and performs run-to-run control (i.e., feedback and feedforward at each process execution) of the process equipment. ARGUS minimizes process variations by detecting and analyzing the changes after each process and then correcting the processing recipe as required.

Most APC software makers provide only a framework, while content, i.e., the data analysis and control programs, are generated by the users themselves. In contrast, ARGUS includes functions for data analysis and process control.

Furthermore, ARGUS incorporates a highly accurate analysis function suitable for many-kinds and small-lot manufacturers, so it enhances overall equipment effectiveness and reduces turnaround time. Costs should be reduced substantially due to decreases in the number of leading wafers and the rework (regeneration) ratio.

*: ARGUS is a registered trademark of New Vision Systems.

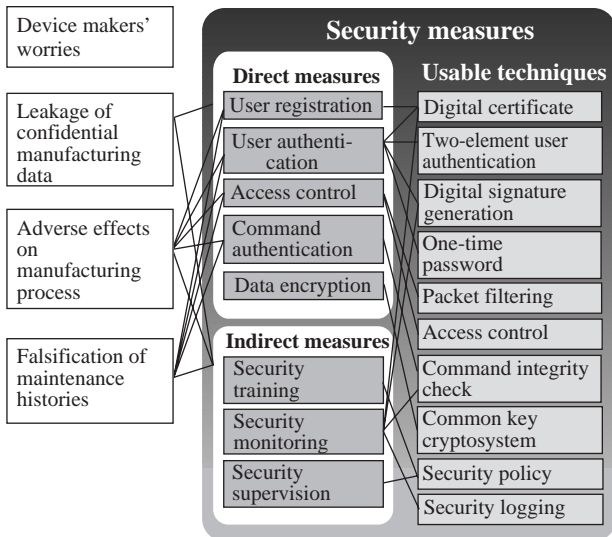


Fig. 6—Security Concerns with e-diagnostics and Hitachi Countermeasures. In e-diagnostics, device makers' confidential data and manufacturing processes can be protected by security measures.

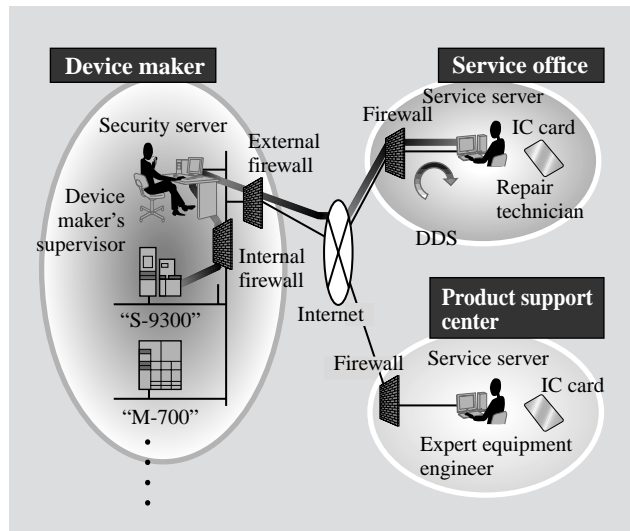


Fig. 7—Example Application of e-diagnostics. Shown here is an example application of e-diagnostics in which a device maker, service office, and product support center are interlinked.

thereby ensuring data security.

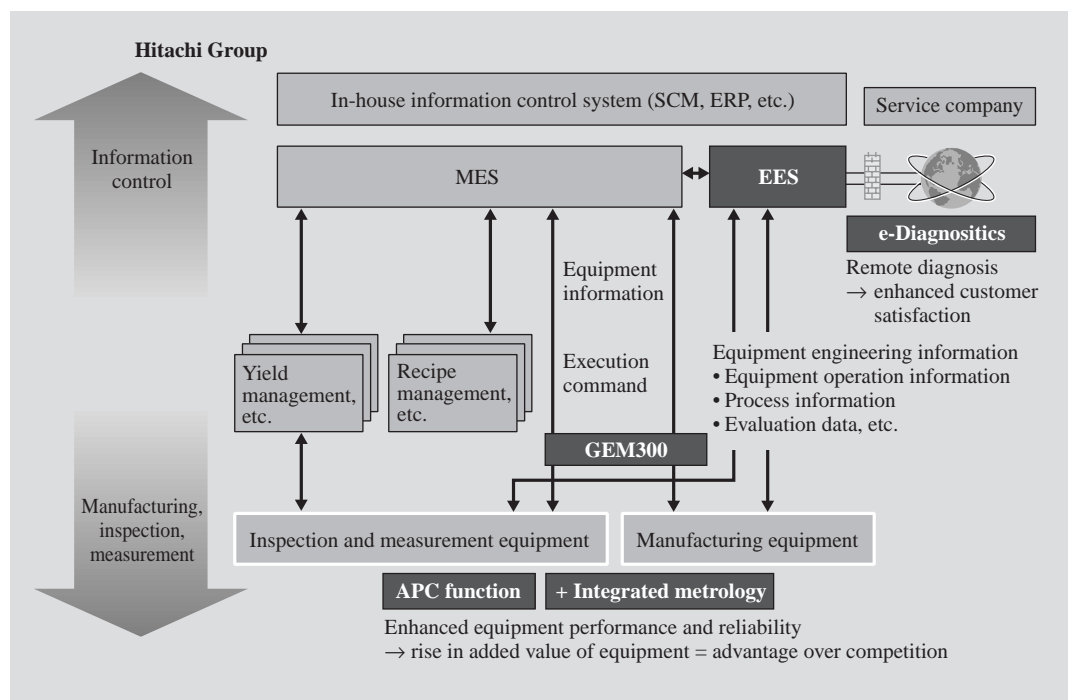
An example e-diagnostics application is illustrated in Fig. 7. The equipment at a device maker's site is connected with a server at a service office. The connection is protected by a security server and two firewalls. Additional security is provided by issuing an IC card to each user. Once a secure connection is established, data acquisition, transmission, and analysis are carried out using a fault analysis system in which a rich variety of information is accumulated

and using troubleshooting software such as defect part diagnostics support. Using the information obtained, the technician can determine the status of a device and identify the problems to be corrected.

TRANSITION FROM EQUIPMENT BUSINESS TO SOLUTION BUSINESS

Fig. 8 illustrates Hitachi's general scheme for a next-generation semiconductor factory and the range of e-manufacturing applications. Hitachi has been

Fig. 8—General Scheme for Next-generation Semiconductor Factory and Range of e-manufacturing Applications. From a broad range of solutions, from leading-edge manufacturing equipment to high-level (information-control) systems, the best solutions will be provided in response to customers' needs.



providing products and systems such as inspection/measurement and manufacturing equipment and yield-enhancement support systems that provide functions and performance matching user requirements. However, customers are now looking for ways to enhance the overall effectiveness of their equipment and reduce chip costs. Responding to this as an equipment supplier, Hitachi has been establishing a business concept and a supply system for presenting the best solutions in e-manufacturing to our customers.

To provide the solutions needed by our customers to implement and support e-manufacturing, we need to switch from being a conventional equipment business to being a "solution business." We are thus working on APC technologies for improving equipment performance and reliability, e-diagnostics systems for enhancing equipment maintenance and servicing, and equipment engineering systems for organically linking and executing APC with e-diagnostics and similar innovations.

Hitachi has the technological capacity to provide the constituent elements of e-manufacturing (information control system group and equipment/system group) as a business and the functions (equipment engineering system, APC, e-diagnostics, etc.) as shown in Fig. 8. By harnessing the synergy between its product and engineering capabilities, Hitachi will be able to offer the best solutions, from leading-edge manufacturing equipment to high-level systems, to our customers.

CONCLUSIONS

We have described advanced process control and e-diagnostics technologies and their expansion to business in the years to come.

Semiconductor-related associations, mainly in Japan and the U.S., are conducting a variety of workshops and undertaking standardization activities for e-manufacturing. Thus, a next-generation semiconductor factory based on e-manufacturing is taking shape.

Hitachi is participating in these activities and helping to popularize e-manufacturing in the electronic parts industry.

ABOUT THE AUTHORS



Yasutsugu Usami

Joined Hitachi, Ltd. in 1984, and now works at the Products Marketing Department, the Device Manufacturing Systems Business Group of Hitachi High-Technologies Corporation. He is currently working on the semiconductor new business creation project. Mr. Usami is the SEAJ EES Committee Chairman and a member of the Vacuum Society of Japan and the Japanese Society of Electron Microscopy, and can be reached by e-mail at usami-yasutsugu@nst.hitachi-hitec.com.



Isao Kawata

Joined Hitachi Tokyo Electronics Co., Ltd. in 1979, and now works at the Process Control Systems Sales 3rd Department, the Semiconductor Process Control Systems Sales Division of Hitachi High-Technologies Corporation. He is currently engaged in the next-generation solution business creation project. Mr. Kawata is a member of SEAJ ESS Committee, and can be reached by e-mail at kawata-isao@nst.hitachi-hitec.com.



Hideyuki Yamamoto

Joined Hitachi, Ltd. in 1984, and now works at the Semiconductor Equipment Design Department, Kasado Division of Hitachi High-Technologies Corporation. He is currently engaged in the development of APC/e-diagnostics technologies for etching systems. Mr. Yamamoto can be reached by e-mail at yamamoto-hideyuki@sme.hitachi-hitec.com.



Hiroyoshi Mori

Joined Hitachi, Ltd. in 1978, and now works at the Electronics Systems Design Department 1, Naka Division of Hitachi High-Technologies Corporation. He is currently engaged in APC system business. Mr. Mori can be reached by e-mail at mori-hiroyoshi@naka.hitachi-hitec.com.



Motoya Taniguchi

Joined Hitachi, Ltd. in 1976, and now works at the R&D Promotion Department, the Group Strategy Division of Hitachi High-Technologies Corporation. He is currently engaged mainly in collaborative work with semiconductor manufacturing equipment-related divisions in Hitachi Group. Dr. Taniguchi is a member of the Japan Society for Precision Engineering, and can be reached by e-mail at taniguchi-motoya@nst.hitachi-hitec.com.